

					2			3		4	
	PRODUCT NO.	POS	POL. POS	DIM X	DIM Y	DIM F	DIM W	PLATING	HSG COLOR		
	90516-001	2 X 2 2	20	42	4 4	4.0	2.5	0.38µm MIN GXT	BEIGE		
	- 002	2 X 3	6	4	6	4.0	3.0	0.76μm MIN GXT	BEIGE		
A	- 0 0 3	2 X I O	8	18	20	4.0	3.0	0.76μm MIN GXT	BEIGE		
	- 0 0 4	2 X I 2	8	22	2 4	4.0	3.0	0.76μm MIN GXT	BEIGE		A
	- 005	2 X 6	8	10	12	4.0	3.0	0.76μm MIN GXT	BEIGE		
	- 0 0 6	2 X I O	3	18	20	4.0	2.45	0.38µm MIN GXT	BEIGE		
	- 0 0 7	2 X 6	-	10	12	3.4	2.5	0.76μm MIN GXT	BEIGE		
	- 008	2 X 6	2	10	12	4.0	2.5	0.76μm MIN GXT	BEIGE		
	- 0 0 9	2 X 3	-	4	6	4.0	2.5	0.76μm MIN GXT	BEIGE		
В	-010	2 X I O	-	18	20	4.0	2.5	0.76μm MIN GXT	BEIGE		
	- 0	2 X 2	3	2	4	4.0	2.5	0.76μm MIN GXT	BEIGE		
	-012	2 X 2		2	4	4.0	3.0	0.76μm MIN GXT	BEIGE		
	-013	2 X 5	3,8	8	10	4.0	3.0	0.76μm MIN GXT	BEIGE		В
	-0 4	2 X I 5	20	28	30	4.0	3.0	0.38µm MIN Au	BEIGE		
	-015	2 X 3	-	4	6	4.0	2.0	0.2μm MIN Au	BEIGE		
	-016	2 X I 5	-	28	30	4.0	2.0	0.2μm MIN Au	BEIGE		
	-017	2 X 4	-	6	8	4.0	2.5	0.76µm MIN Au	BEIGE		
	-018	2 X 5	-	8	10	4.0	2.5	0.76µm MIN Au	BEIGE		
<b>F</b>	-0 9	2 X 2 3	5,6,11,12,17,18,23,24 29,30,35,36,41,42	4 4	46	4.0	3.0	0.76μm MIN GXT	BEIGE		
	- 020	2 X 3	4	4	6	4.0	2.5	0.76µm MIN Au	BEIGE		С
	- 021	2 X 4	4	6	8	4.0	2.5	0.76µm MIN Au	BEIGE		
	- 022	2 X 5	5,6	8	10	4.0	3.0	0.76μm MIN GXT	BEIGE		
	- 023	2 X 7	8	12	4	4.0	3.0	0.76μm MIN GXT	BEIGE		
	- 0 2 4	2 X 7	8	12	4	4.0	3.0	0.38µm MIN GXT	BEIGE		
	- 025	2 X 2 0	-	38	40	1.8	2.5	0.76µm MIN GXT	BLACK		
Copyright FCI.	SEV F - 2006-04-17							WWW.fciconnect.com    Surface -   tolerance std   projection   MM			D

PDM: Rev:T STATUS Released Printed: Oct 12, 2010

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В

XXXXX-XXXLF

-LEAD FREE. SEE NOTE 7 - EXTENSION NUMBER -BASE NUMBER

RECESS APPLIES TO MOLDED SIDE(S) ONLY.

SAW, DIM 0.5 MIN APPLIES.

PRODUCT DESCRIPTION CODE :

P/N:90516-XXXLF IS SAME AS P/N:90516-XXX. THE SUFFIX 'LF' IS ADDED JUST FOR EASY LEAD FREE IDENTIFICATION.

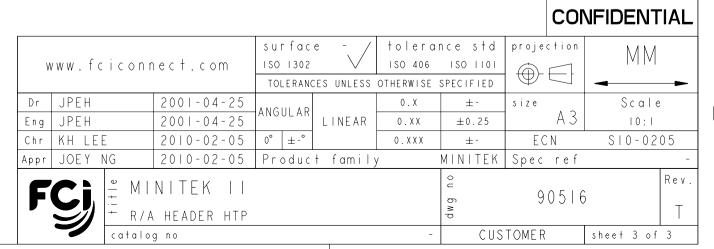
DIM 1.0 APPLIES TO MOLDED SIDE(S) ONLY. IF SIDE(S) ARE

8. THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.

9. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.

IO. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

11. A 1 SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.



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